# **APPROVAL SHEET**

## CrossAir<sup>™</sup> SMD Antenna series RoHS Compliance

PN: CA-C03

## 2.4 GHz ISM band antenna

Company: HWJELEC

Address:1119,11/F, Hongda Creative Garden, no.

96 Yuan Xiang Road, Yunpu Street, Huangpu

**District**, Guangzhou City

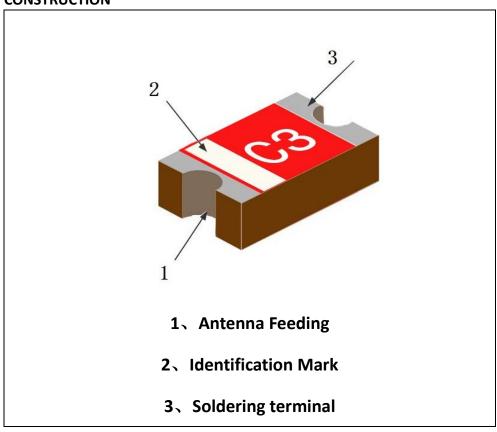
#### **FEATURES**

- 1. Surface Mounted Devices (SMD) with a small dimension of 5.5  $\times$  2.0  $\times$  1.0 mm $^3$  meet miniaturization trend.
- 2. Low power loss and high antenna efficiency.
- 3. High stability in Temperature and Humidity Change.

## **APPLICATIONS**

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, ZigBee, Wireless, HomeRF
- 3. WIFI (2.4G only)

## **CONSTRUCTION**



## **DIMENSIONS**

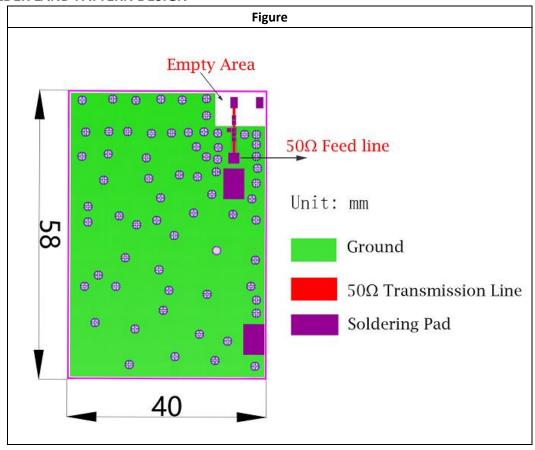
Figure	Symbol	Dimension(mm)	
a=0.5 (mm) 	L	<b>5.5</b> ±0.1	
	w	<b>2.0</b> ±0.1	
L= 5.5 (mm) T=1.0 (mm)	Т	<b>1.0</b> ±0.1	
	а	<b>0.5</b> ±0.1	

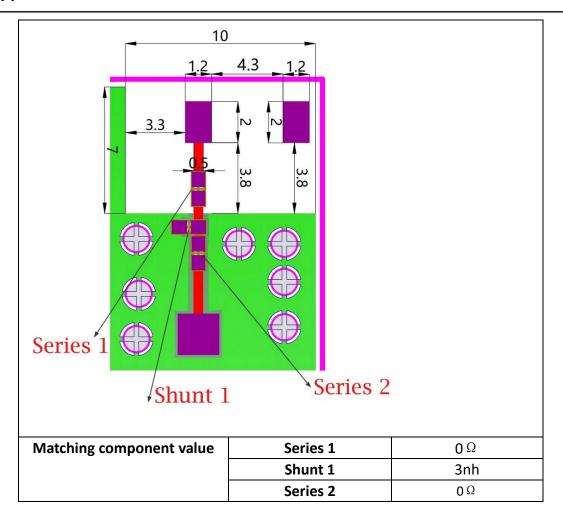
## **ELECTRICAL CHARACTERISTICS**

CA-C03	Specification	
Working Frequency Range	<b>2450</b> ± 50MHz	
Fc(GHz)	2.45GHz	
Band Width	>100MHz	
Impedance	50 Ω	
Gain(dBi)	4.3 (peak)	
VSWR	<2	
Operation Temperature	-40℃~+95℃	
Power Capacity	apacity 3W	

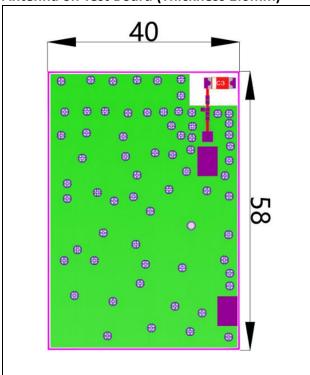
The working frequency need be adjusted to 2.45GHz with matching circuit.

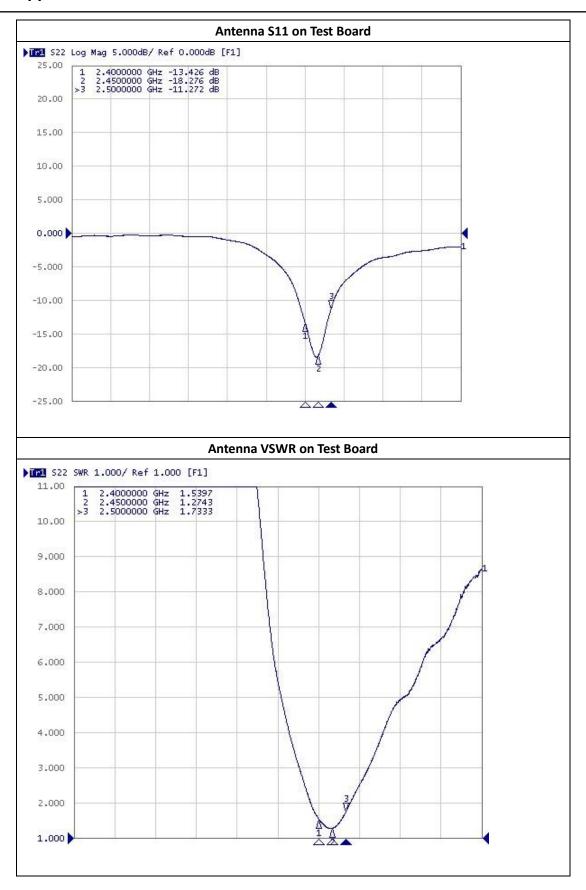
## **SOLDER LAND PATTERN DESIGN**





## Antenna on Test Board (Thickness 1.0mm)

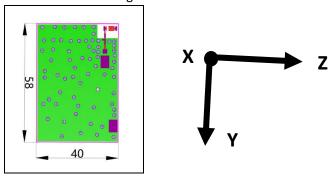




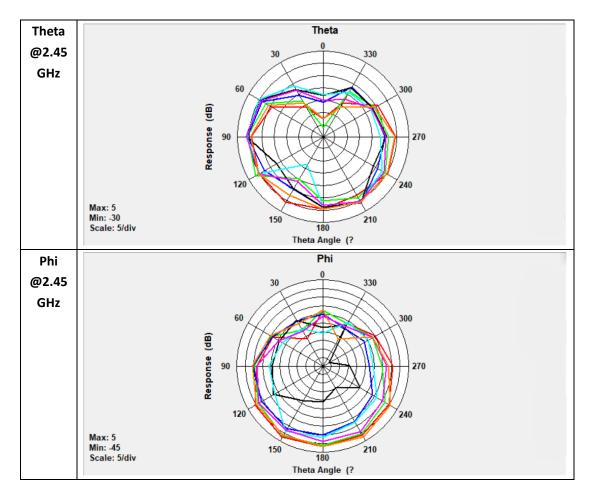
## **Efficiency and RADIATION PATTERN**

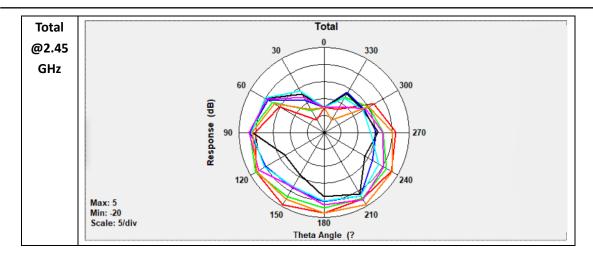
Efficiency, Radiation Pattern and Gain were dependent on measurement board design. The

specification of CA-CO3 antenna was measured based on the PCB size and installation position as shown in the below figure test board. The test results were tested in ETS 3D Chamber.



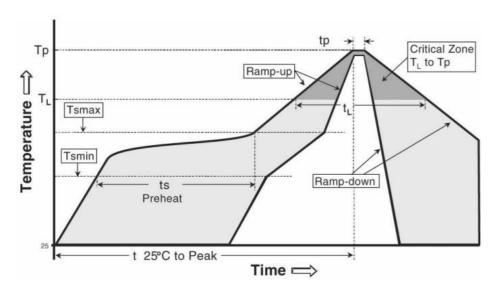
Gain and Efficiency	2.4G-2.5GHz		
Peak Gain	4.3dBi		
Average Gain across the band	4.1dBi		
Gain Range across the band	3.9dBi~4.3dBi		
Peak Efficiency	81.7%		
Average Efficiency across the band	80.2%		
Efficiency Range across the band	78.6%~81.7%		





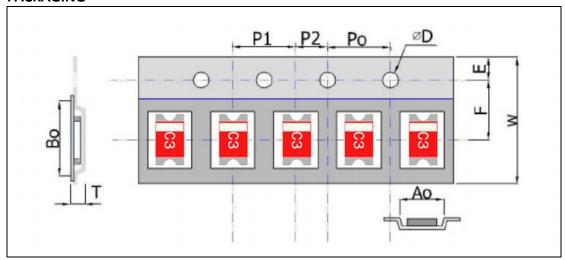
## **SOLDERING CONDITION**

Typical examples of soldering processes that provide reliable joints without any damage is as follows:



Phase	Profile features	Pb-Free assembly (SnAgCu)		
RAMP-UP	Avg. Ramp-up Rate (Tsmax to Tp)	3 °C / second (max.)		
PREHEAT	- Temperature Min (Tsmin) - Temperature Max (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 seconds		
REFLOW	- Temperature (TL) - Total Time above TL (tL)	217 °C 60-150 seconds		
PEAK	- Temperature (Tp) - Time (tp)	260 °C 20-40 seconds		
RAMP-DOWN	Rate	6 °C/second max		
Time from 25 °C to Peak Temperature		8 minutes max		

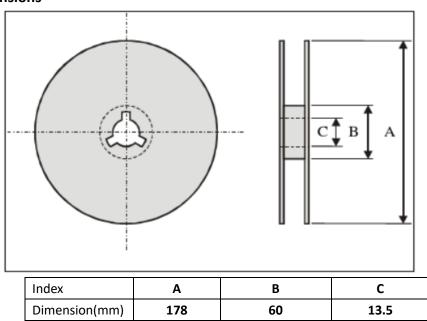
## **PACKAGING**



## Plastic Tape specification (unit:mm)

Index	Ao	Во	Фр	Т	w
Dimension (mm)	3.0±0.1	6.0±0.1	1.55±0.05	1.2±0.1	11.8±0.1
Index	E	F	Ро	P1	P2
Dimension (mm)	1.75±0.1	4.6±0.1	4.0±0.1	4.0±0.1	2.0±0.1

## **Reel dimensions**



Typing Quantity: 3000 pieces per reel.

## **CAUTION OF HANDLING**

## Storage environment condition

Products shoud be storage in the warehouse on the following conditions:

## **Approval** sheet

Temperature :  $-10^{\circ}$ C ~+40  $^{\circ}$ C

Humidity : 30% to 70% relative humidity

Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.

Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.

Products should be storage under the airtight packaged condition.